MICROCONTROLLERS PART NUMBERING GUIDE

MB 90 F 5 9 8 GA PF -9001 G -BND -ER

Tape Specifications
ER = Right Facing Tape/Reel
EF = Left Facing

Lead Form
BND - Bend Lead
STR - Straight Lead
SH - Shrink Pitch

Category
G - General

Custom Code
xxx - Mask Rom
5xx - OTP Programmed
9xxx - Flash Programmed

Package Suffix
P = Plastic DIP
PF = Plastic QFP/SOP
C = Ceramic DIP
CF = Ceramic QFP
PFM = Plastic QFP/LQFP
PFM = Plastic QFP/LQFP
PMT = Plastic QFP/LQFP
PFV = Plastic QFP/LQFP
PFS = Plastic QFP
CR = Ceramic PGA
PFF = Plastic LQFP

Device Series
Three numbers designate the device series with the options of two letter variations.

Possible numbers: 101 to 999 (Customer specific)
Possible letters: A, B, C, G, H, L, R, HC (Revisions)

Memory Type
Blank = Mask ROM
F = Flash ROM
P = OTP ROM
T = External ROM
V = Evaluation Device
FV - Flash/Evaluation
M - Mult: Chip Module
MF - Mult: Chip Module/Flash
W = EPROM

Number of Bits
89= 8 bit, ASSP
90= 16 bit, ASSP (OSDC)
91= 32 bit ASSP

Fujitsu Semiconductor ID
MB = Micro Block